## Beam test results from the Large Prototype TPC with GEM modules

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MOTIVATION	SETUP	ANALYSIS	FUTURE PLAN
Performance g	oal of the LC-TP	С	
1. $e^+e^- \rightarrow ZE$	$I(Z \to \mu \mu/ee) + X$	(Recoil mass measur	ement)
a. $H  ightarrow \mu \mu$		(Rare decay Br. meas	urement)
To measure Higgs tracker should hav point (if $B = 3 \sim 4T$ ) Two track separat	mass with ~100MeV re 200 measurement ). ion is also important	accuracy by these proposed points and 50~100µm	energy resolution.
Recoil mass met left : Performance right : Present per $a=2.0 \times 10^{-4}$ $b=1.0 \times 10^{-1}$ $M_{h}=103 \text{ MeV}$	asurement Rare decay H re goal erformance $H \rightarrow \mu \mu$ $a = 8.0 \times 10^{-3}$ $\Delta M_{a} = 273 \text{ MeV}$	Br. measurement $H \rightarrow \mu^* \mu^-$ $\sqrt{s} = 0.8 \text{ TeV}$ PFA: recognized $V$	nition of jet clusters

140 145 150 155 μ<sup>+</sup>μ<sup>-</sup> Mass (GeV) Ecole n/que

10

<sub>0</sub> ا

115 120 125 130 135

9 60 1 40

20

0 E 100 120 140 Recoil Mass (GeV) 20

160

0 E 120 140 Recoil Mass (GeV)

100

-

MOTIVATION

#### TPC Large Prototype (LP1) Beam Test at DESY using EUDET Facility

#### Goals of LP1 Beam Test

• To study, in practice, design and fabrication of all components of MPGD TPC in larger scale; field cage, endplate, detector modules, front end electronics, and field mapping of non uniform magnetic field.

• To demonstrate full-volume trucking in non-uniform magnetic field, trying to provide a proof for the momentum resolution at LC TPC

- To demonstrate dE/dX capability of MPGD TPC
- To study effects of detector boundaries
- To develop methods and software for tracking, alignment, calibration, and corrections



Field cage (DESY)

Maximum drift length  $\sim$  60 cm Diameter  $\sim$  70 cm

Readout modules are prepared several sub-groups

- GEM (Asia, Bonn, DESY)
- Micromegas (Saclay/Canada)
- TimePix (NIKHEF, Bonn)

Calibration has been done by Victoria University.





Magnet (KEK)

Magnet

- B = 1T
- thickness  $20\% X_0$
- moving table with linear scaler





GEM module with "Field shaper"

... Real life

Since transmission efficiency of our gating device is at most 50% so far, we tested the module without gating device at this moment.

To match our modules to LP1 endplate, we prepared "Field shaper" instead of gating device.

PCBs designed and produced by **Tsinghua University** 

ANALYSIS

FUTURE PLAN

## Readout electronics

PCA16 + ALTRO electronics are developed by **Lund University** / **CERN**. (which are originally built on ALICE TPC readout.)

A channel

programable gain, shaping time and polarity
1000 samples, 10 bit

resolution, 20 MHz sampling

In this beam test, we used 7616 channels with air cooling system and temperature monitoring system for electronics. Readout electronics mounted to LP1



MOTIVATION	SETUP	ANALYSIS	FUTURE PLAN
Analysis fran Two reconstructi	nework on software.		
• Common analys:	is software • • • Mai	clin TPC	
	Wit a	h Track-Making-Kalman-Filte Igorithm is used both in track	r -Processor, Kalman filter finding and track fitting
	Ing	out data format : lcio	
• Local analysis so	oftware ••• yok	aRawMon	

Input data format : rawdata (binary)

Kalman filter algorithm is used only in track fitting

At this moment, since there is no way to read LCIO format (reconstructed data by Marlin TPC) with ROOT framework, I used yokaRawMon for this report.



Since this is useful to check the system, Marlin TPC also should have this kind of event display.



MOTIVATION	SETUP	ANALYSIS	FUTURE PLAN

#### Point resolution



MOTIVATION	SETUP	ANALYSIS	FUTURE PLAN

#### Momentum resolution



used Marlin TPC without any aliment correction

MOTIVATION	SETUP	ANALYSIS	FUTURE PLAN

## Summary

We tested multi GEM module readout system.

- gas property were checked.
- point resolution
- momentum resolution

### Future plan

software development (Marlin TPC) beam test with pion beam beam test with new electronics (s-ALTRO) Advanced end plate electronics bump bonding electronics CO<sub>2</sub> cooling

#### SETUP

ANALYSIS

FUTURE PLAN

Micromegas module:

## Some comments for Advanced endplate R&D

For next beam test, we are developing new electronics.

The electronics will be implemented in high density to reduce amount of materials. (Goal : thickness  $15\% X_0$ )

There will be heat problem due to high density electronics.

To solve this problem,



electronics behind module!

we are considering to use 2 phase  $CO_2$  cooling system, which can achieve temperature uniformity and low amount of materials. We are preparing FPGA dummy board, which generates heat instead of the real front end board, and planing to do a cooling test with the dummy board at NIKHEF. At the same time, the infrastructures for the  $CO_2$  cooling test are being prepared at KEK.

Another essential thing to solve heat problem is power pulsing. We are also planing to do power pulsing test with FPGA dummy board.

# Backup